PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Toshinari MURAI	08/21/2006
Yukio SHIBANO	08/21/2006

RECEIVING PARTY DATA

Name:	Shin-Etsu Chemical Co., Ltd.
Street Address:	6-1, Otemachi 2-chome, Chiyoda-ku,
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11468570

OP $40.00 11468570

CORRESPONDENCE DATA

Fax Number: (202)822-1111
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: 2028221100
Email: PatentMail@Whdapatentlaw.com
Correspondent Name: Westerman, Hattori, Daniels & Adrian LLP
Address Line 1: 1250 Connecticut Avenue NW,
Address Line 2: Suite 700
Address Line 4: Washington,, DISTRICT OF COLUMBIA 20036

ATTORNEY DOCKET NUMBER:	063004
NAME OF SUBMITTER:	Stephen G. Adrian

Total Attachments: 1
source=063004Assignment#page1.tif

Docket No. _____ **Westerman, Hattori, Daniels & Adrian, LLP**

U.S. ASSIGNMENT

IN CONSIDERATION of the sum of One Dollar ($1.00), and of other good and valuable consideration paid to the undersigned inventor(s) (hereinafter ASSIGNOR) by

(Insert ASSIGNEE's Name(s) Address(es))

Shin-Etsu Chemical Co., Ltd. of
6-1, Otemachi 2-chome, Chiyoda-ku, Tokyo, Japan

(hereinafter ASSIGNEE), the receipt of which is hereby acknowledged, the undersigned ASSIGNOR hereby sells, assigns and transfers to ASSIGNEE the entire and exclusive right, title and interest to the invention entitled

(Title of Invention)

Wafer Polishing Method and Polished Wafer

(*If the assignment is being filed after the filing of the application, this section must be completed)

for which application for Letters Patent of the United States was executed on even date herewith unless otherwise indicated below:

* filed on ____________________ Serial No. ____________________

(**Westerman, Hattori, Daniels & Adrian, LLP** is hereby authorized to insert the series code, serial number and/or filing date hereon, when known)

and all Letters Patent of the United States to be obtained therefore on said application or any continuation, divisional, substitute, reissue or reexamination thereof for the full term or terms for which the same may be granted.

The ASSIGNOR agrees to execute all papers necessary in connection with the application and any continuation, divisional, reissue or reexamination applications thereof and also to execute separate assignments in connection with such applications as the ASSIGNEE may deem necessary or expedient.

The ASSIGNOR agrees to execute all papers necessary in connection with any interference, litigation, or other legal proceeding which may be declared concerning this application or any continuation, divisional, reissue or reexamination thereof or Letters Patent or reissue patent issued thereon and to cooperate with the ASSIGNEE in every way possible in obtaining and producing evidence and proceeding with such interference, litigation, or other legal proceeding.

(Signatures)

IN WITNESS WHEREOF, the undersigned inventor(s) has (have) affixed his/her/their signature(s).

Toshinari Murai	Toshinari MURAI	August 21, 2006
(Signature)	(Type Name)	(Date)
Yukio Shibano	Yukio SHIBANO	August 21, 2006
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)
(Signature)	(Type Name)	(Date)

NO LEGALIZATION REQUIRED